# Nch 100V 200A Wide-SOA Power MOSFET

$V_{DSS}$	100V
R <sub>DS(on)</sub> (Max.)	4.0mΩ
I <sub>D</sub>	±200A
$P_D$	217W

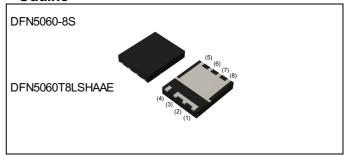
## Features

- 1) Low on resistance
- 2) High power package (DFN5060T8LSHAAE)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen free
- 5) 100% Rg and UIS tested
- 6) Wide-SOA

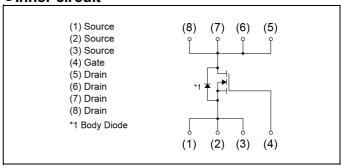
# Application

Hot Swap Controller(HSC)

# Outline



# •Inner circuit



Packaging specifications

	ing opcomoducino	t
	Packing	Embossed Tape
	Reel size (mm)	300
Туре	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	TB1
	Marking	RS7P200BM

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	100	V
Continuous drain current V <sub>GS</sub> = 10V	I <sub>D</sub> *1	±200	А
Pulsed drain current	I <sub>DP</sub> *2	±800	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	44	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	150	mJ
Davier discinction	P <sub>D</sub> *1	217	W
Power dissipation	P <sub>D</sub> *4	3.6	W
Junction temperature	Tj	175	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +175	°C

## ●Thermal resistance

Doromotor	Symbol	Values			Lleit
Parameter		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	0.69	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	41.7	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Parameter Symbol Conditions		Values			l lait
Parameter			Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	100	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	58.4	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	1	1	5	μA
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	ı	1	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 1mA$	2.0	-	4.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}} I_{D} = 1 \text{mA}$ referenced to 25°C		-	-5.6	-	mV/°C
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A	-	3.1	4.0	mΩ
Gate resistance	$R_G$	-	0.7	1.3	2.6	Ω
Forward Transfer Admittance	$ Y_{fs} ^{*5}$ $V_{DS} = 5V, I_D = 50A$		18	-	-	S

<sup>\*1</sup>  $T_c$ =25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s , Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Uill	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	*3330	5550	*7800		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 50V	*530	880	*1240	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	*14	27	*55		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 50V, V_{GS} = 10V$	-	53	-		
Rise time	<b>t</b> <sub>r</sub> *5	I <sub>D</sub> = 50A	-	40	-	no	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 1.0Ω	-	67	-	ns	
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	51	-		

<sup>\*:</sup> Guarantee of Design

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Lloit
			Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≈ 50V,	*44.0	72.0	*105.0	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 50A,	*15.6	26.0	*37.0	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	*6.1	12.2	*25.0	

<sup>\*:</sup> Guarantee of Design

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
		Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub> *1		-	-	180	Α
Pulse forward current	$I_{SP}^{*2}$	-	-	-	800	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 50A$	-	-	1.2	V
Reverse recovery time	<b>t</b> <sub>rr</sub> *5	I <sub>S</sub> = 50A, V <sub>GS</sub> =0V	-	77	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	160	-	nC

### • Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

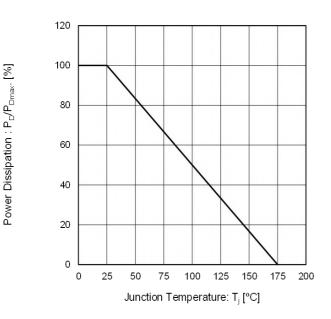
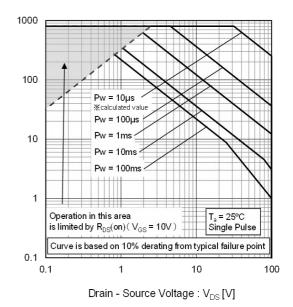


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

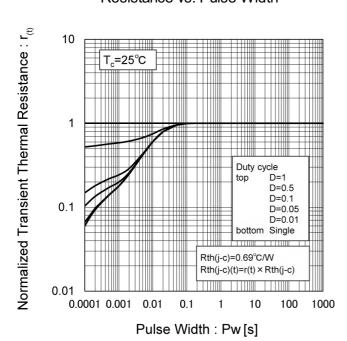
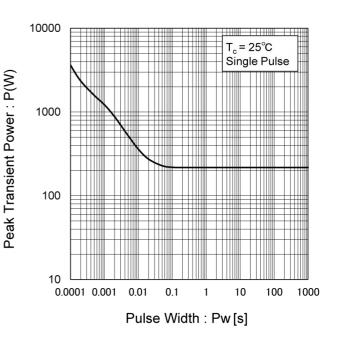


Fig.4 Single Pulse Maximum Power Dissipation



Drain Current : I<sub>D</sub> [A]

Normalized Breakdown Voltage :  $V_{(BR)DSS}$ 

### • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

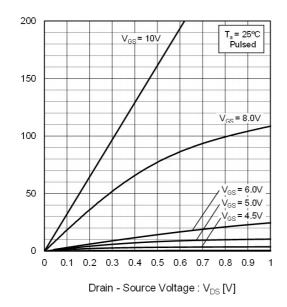
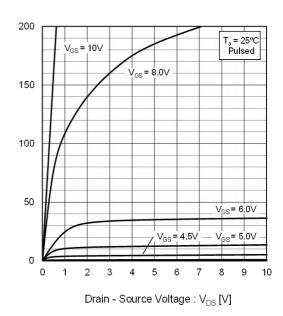


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

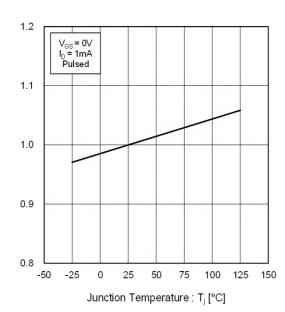
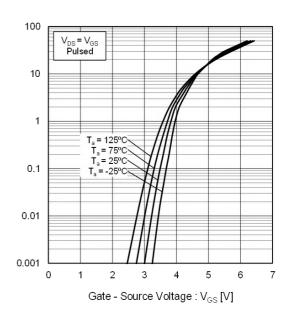


Fig.8 Typical Transfer Characteristics



Drain Current : I<sub>D</sub> [A]

Gate Threshold Voltage :  $V_{GS(th)}[V]$ 

### • Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

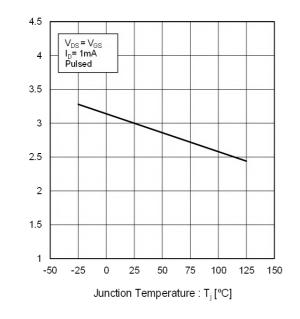


Fig.10 Forward Transfer Admittance vs.

Drain Current

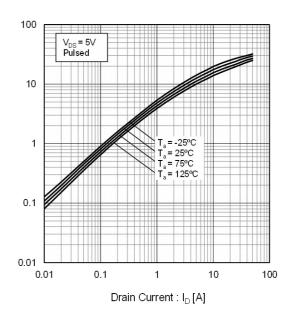


Fig.11 Drain Current Derating Curve

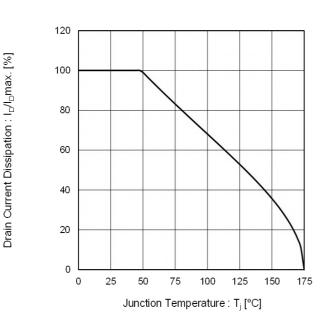
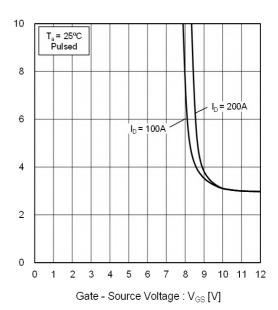


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance :  $R_{\text{DS}(\text{on})} \left[ \text{m} \Omega \right]$ 

Forward Transfer Admittance : Y<sub>fs</sub> [S]

### • Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

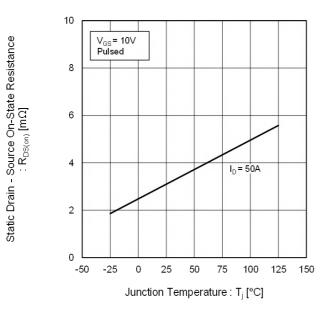
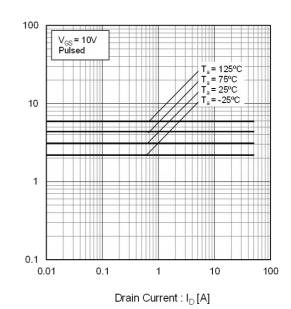


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (II)



Static Drain - Source On-State Resistance :  $R_{\mathrm{DS(on)}}[m\Omega]$ 

Fig.15 Typical Capacitances vs.

Drain - Source Voltage

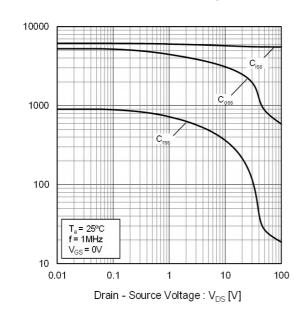
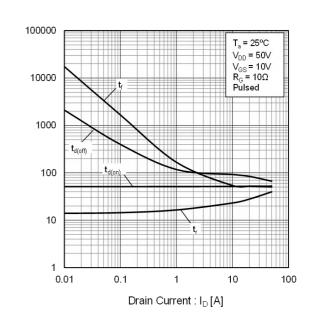


Fig.16 Switching Characteristics



Capacitance : C [pF]

Switching Time : t [ns]

# • Electrical characteristic curves

Fig.17 Typical Gate Charge



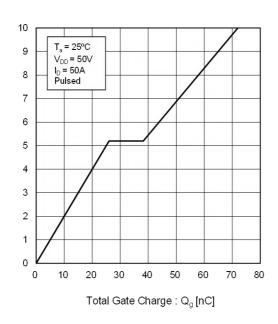
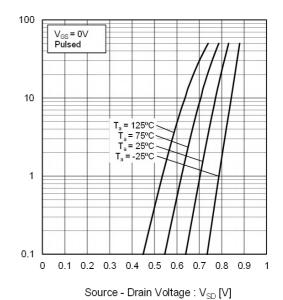


Fig.18 Source Current vs.
Source Drain Voltage



Source Current : I<sub>s</sub> [A]

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## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

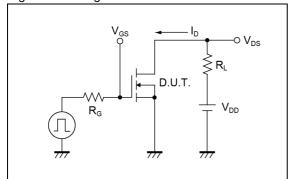


Fig.1-2 Switching Waveforms

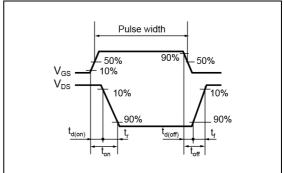


Fig.2-1 Gate Charge Measurement Circuit

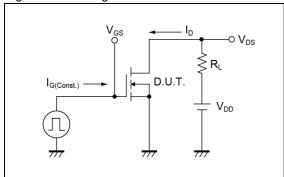


Fig.2-2 Gate Charge Waveform

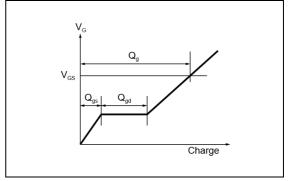


Fig.3-1 Avalanche Measurement Circuit

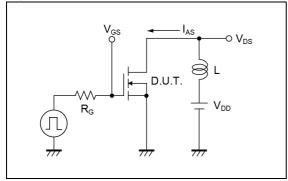
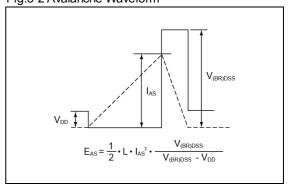


Fig.3-2 Avalanche Waveform



# Dimensions

#### DFN5060-8S DFN5060T8LSHAAE D D2 1 E ш 8 0 Nx b е + bbb M C A B b1 Seating plane ₽ 12 3 b2 2 b3 [reference pattern of soldering pads] Milimeters Inches DIM Min. Max Min 1.10 0.043 Α 0.05 0.002 A1 С Ь 0.34 0.54 0.013 0.021 5.10 4.35 0.201 D 4.90 0.193 D2 4.15 0.163 0.171 5.90 6.10 0.232 E 0.240 E1 4.00 4.20 0.157 0.165 E3 0.20 0.40 0.008 0.016 e 0.050 0.60 0.80 0.024 0.031 L L1 0.53 0.021 0.010 N 0.004 0.10 bbb 0.003 0.08 ccc Milimeters Inches DIM Nom. Nom. Ь1 4.45 0.175 1.27 0.050 **b2** Ь3 0.64 0.025 0.72 11 0.028 12 4.58 0.180 6.60 13 0.260 14 1.13 0.044 15 0.50 0.020 Dimension in mm / inches

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CLASSIV		CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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